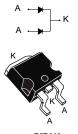




100 V, 2 x 30 A field-effect rectifier diode



Features



- AEC-Q101 qualified
- PPAP capable
 Operating T_i from -40 °C to 175 °C
- · ST patented rectifier process
- Stable leakage current over reverse voltage
- · Low forward voltage drop
- · High frequency operation
- ECOPACK compliant

Applications

- · Battery charger
- DC / DC converter
- OBC (on-board battery charger)
- PHEV EV charging station
- Resonant LLC topology
- PFC functions (power factor correction)

Product status link FERD60H100C-Y

Product summary			
I _{F(AV)}	2 x 30 A		
V_{RRM}	100 V		
T _j (max.)	175 °C		
V _F (typ.)	0.64 V		



Description

The FERD60H100C-Y is based on proprietary technology that achieves the best in class V_F/I_R trade-off for a given silicon surface.

This 100 V automotive diode has been optimized for use in confined applications where both efficiency and thermal performance are key parameters.

This device is suitable to be used in DCDC converter by improving the efficiency.



1 Characteristics

Table 1. Absolute ratings (limiting values per diode at 25 °C, unless otherwise specified)

Symbol	Parameter			Value	Unit
V_{RRM}	Repetitive peak reverse voltage (T _j = -40 °C to +175 °C)			100	V
I _{F(RMS)}	Forward rms current			60	Α
le.n.o	Average forward average	$T_{\rm c} = 145 ^{\circ}{\rm C}, \delta = 0.5$	Per diode	30	Α
I _{F(AV)} Average forward current	1 _C = 143 C, 0 = 0.3	Per device	60		
I _{FSM}	Surge non repetitive forward current $t_p = 10 \text{ ms sinusoidal}$			290	Α
T _{stg}	Storage temperature range	-65 to +175	°C		
Tj	Operating junction temperature range			-40 to +175	°C

Table 2. Thermal resistance parameters

Symbol		Paramete	_	Va	Unit	
	Symbol P			Тур.	Max.	Offic
D.,	lunction to coop	Per diode	0.60	1.06	°C/W	
	R _{th(j-c)}	Junction to case	Per device	0.30	0.53	C/VV

For more information, please refer to the following application note:

AN5088: Rectifiers thermal management, handling and mounting recommendations

Table 3. Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Тур.	Max.	Unit
I _R ⁽¹⁾ Reverse leakage current		T _j = 25 °C	V - V		60	μΑ
	Reverse leakage current	T _j = 125 °C	$V_R = V_{RRM}$		10	mA
		T _j = 125 °C	V _R = 70 V		5	mA
		T _j = 25 °C	I _F = 5 A	0.46	0.52	
		T _j = 125 °C		0.41	0.45	
		T _j = 25 °C	I _F = 15 A	0.62	0.70	
V (2)		T _j = 125 °C		0.56	0.61	.,,
V _F ⁽²⁾ Forward voltage drop	T _j = 25 °C	I _F = 30 A	0.75	0.85	V	
	T _j = 125 °C		0.64	0.70		
		T _j = 25 °C	I _F = 60 A	0.92		
		T _j = 125 °C	IF - 60 A	0.76		

- 1. Pulse test: $t_p = 5$ ms, $\delta < 2\%$
- 2. Pulse test: t_p = 380 μ s, δ < 2%

To evaluate the conduction losses, use the following equation: $P = 0.55 \times I_{F(AV)} + 0.005 \times I_{F}^{2}_{(RMS)}$ For more information, please refer to the following application notes related to the power losses:

- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

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1.1 Characteristics (curves)

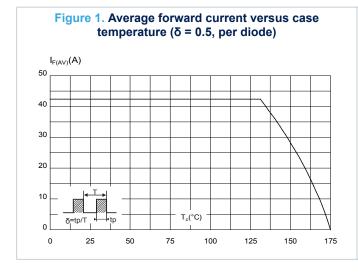


Figure 2. Relative variation of thermal impedance junction to case versus pulse duration $Z_{th(j-c)}/R_{th(j-c)}$ 1.0 0.9 0.8 0.7 0.6 0.5 0.4 0.3 0.2 1.E-04 1.E-03 1.E-02 1.E-01 1.E+00

Figure 3. Reverse leakage current versus reverse voltage applied (typical values, per diode)

I_R(μA)

1.E+05

1.E+04

1.E+03

1.E+03

1.E+00

1.E+00

1.E+00

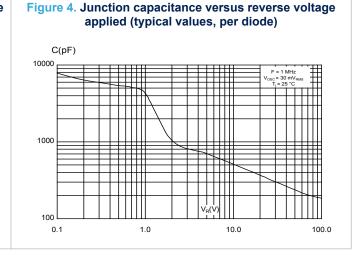
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1.E+01



(typical values, per diode)

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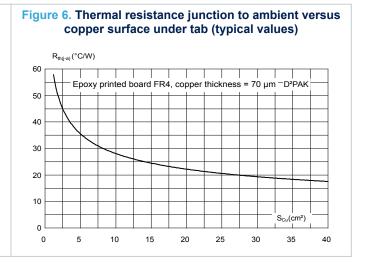
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Figure 5. Forward voltage drop versus forward current



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2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

2.1 D²PAK package information

- Epoxy meets UL94, V0.
- Cooling method: by conduction (C)

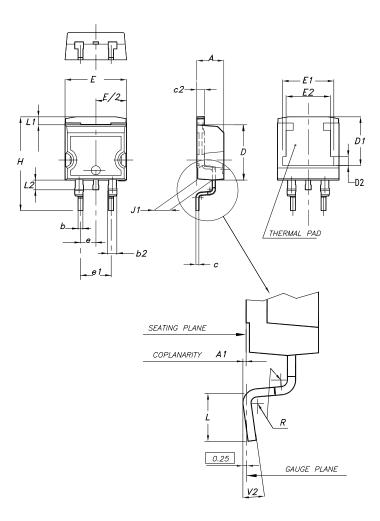


Figure 7. D²PAK package outline

Note: This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

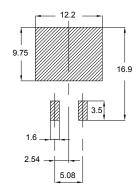
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Table 4. D²PAK package mechanical data

	Dimensions					
Ref.	Millimeters			Inches (for reference only)		
	Min.	Тур.	Max.	Min.	Тур.	Max.
А	4.40		4.60	0.173		0.181
A1	0.03		0.23	0.001		0.009
b	0.70		0.93	0.028		0.037
b2	1.14		1.70	0.045		0.067
С	0.45		0.60	0.018		0.024
c2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1	7.50	7.75	8.00	0.295	0.305	0.315
D2	1.10	1.30	1.50	0.043	0.051	0.060
E	10.00		10.40	0.394		0.409
E1	8.30	8.50	8.70	0.335	0.343	0.346
E2	6.85	7.05	7.25	0.266	0.278	0.282
е		2.54			0.100	
e1	4.88		5.28	0.190		0.205
Н	15.00		15.85	0.591		0.624
J1	2.49		2.69	0.097		0.106
L	2.29		2.79	0.090		0.110
L1	1.27		1.40	0.049		0.055
L2	1.30		1.75	0.050		0.069
R		0.40			0.015	
V2	0°		8°	0°		8°

Figure 8. D²PAK recommended footprint (dimensions are in mm)



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3 Ordering information

Table 5. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
FERD60H100CGY-TR	FD60H100CGY	D²PAK	1.38 g	1000	Tape and reel

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Revision history

Table 6. Document revision history

Date	Revision	Changes	
25-Mar-2021	1	First issue.	
06-Apr-2021	2	Updated Features and Applications.	

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